



Product / Process Change Notification (PCN)

- ☒ Major Change
☐ Minor Change

PCN Number: PCN_IndPDA_20250210

Affected Series: WE-PDA-1260

Affected Order Codes: See table below

PCN Date: 2024-08-10 (YYYY-MM-DD)

Effective Date: 2025-02-10 (YYYY-MM-DD)

Change Category:

- ☐ Equipment/Location
☐ General Data
☒ Material
☒ Process
☒ Product Design
☐ Shipping/Packaging
☐ Supplier
☐ Software

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Datasheet Change:

- ☒ Yes ☐ No

Attachment:

- ☐ Yes ☐ No

Description of Change:

In order to enhance the product reliability, Würth Elektronik eiSos has improved the product design by updating the shield ring and base of the component. A new glue supplier is released as a second source. A new manufacturing line has been released with a higher degree of automation. The temperature range of the component has been improved to -50 °C up to 150 °C.

There will be no change in function of the product. There will be no change of electrical parameters.

The new revision of the affected order codes will be sent out after the previous revision is out of stock (according to FIFO - first-in, first-out).

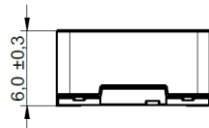
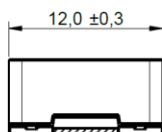
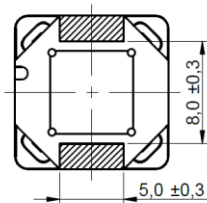
Affected order codes:

784771010	784771068	784771330	784771221
784771022	784771082	784771470	784771331
784771033	784771100	784771680	784771471
784771047	784771220	784771101	784771102

Details of Change:

Before Change

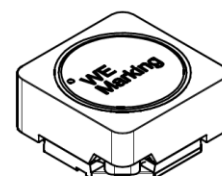
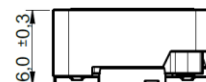
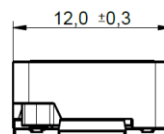
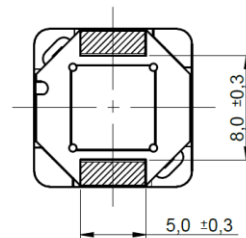
The original component has a different shield ring, base and ink marking. The operating temperature range was from -40 °C to 125 °C.



Scale - 2:1

After Change

The correction consists of an improvement in the shield ring and base and a change from ink marking to laser marking. The operating temperature range will be improved from -50 °C to 150 °C.



Scale - 2:1



Reliability / Qualification of Change:

An additional reliability testing was performed and approved.

Qualification according to AEC-Q200 RevE table 05.

Additional details of the tests can be found in the table below:

Test Item	Sample Size	Reference	Test Conditions	Acceptance
High Temperature Exposure	77	MIL-STD-202-108	150 °C, 1000 h	Approved
Temperature Cycling	77	JESD22 Method JA-104	preconditions: Reflow passes required -40 °C to 125 °C, dwell time: 15 minutes minimum, Transfer time max. 1min., 1000 cycles	Approved
Humidity Bias	77	MIL-STD-202-103	preconditions: Reflow passes required 85 °C, 85 % RH, 1000 h	
High Temperature Operational Life	77	MIL-STD-202-108	preconditions: Reflow passes required 110 °C=150 °C – 40 K, 1000 h, maximum rated current with derating	Approved
External Visual	All	MIL-STD-883-2009	N/A	Approved
Physical Dimension	77	JESD22 Method JB-100	N/A	Approved
Resistance to Solvents (Wsh 3.1 Washability)	5	MIL-STD-202-215	preconditions: soldered on PCB. Step1: Cleaning with medium A201 @ 60 °C, 20 min (pre-heated on min.45 °C) Step2: Rinsing 1 with DI water @ 30 °C, 2 min Step3: Rinsing 2 with DI water @ 30 °C, 2 min Step4: Rinsing 3 with DI water @ 40 °C, 3 min Step5: Rinsing 4 with DI water @ 50 °C, 3 min Step6: Drying @ 90 °C, 30 min Unpowered.	Approved
Mechanical Shock	30	MIL-STD-202-213	shocks in each direction (x, -x, y, -y, z, -z), total 18 shocks, peak value 100 g's, duration 6ms, half-sine, velocity change 12.3 ft/sec.	Approved
Vibration	30	MIL-STD-202-204	5 g for 20 min, 12 cycles each of 3 orientations. Test from 10 Hz to 2000 Hz.	Approved

(please see next page)



Test Item	Sample Size	Reference	Test Conditions		Acceptance
Resistance to Soldering Heat	30	J-STD-020	Tc=245 °C, tp=30~35 s, 5 times reflow		Approved
ESD	15	AEC-Q200-002 or ISO/DIS10605	Test Environment: 22 °C ± 5 °C, Humidity: 30 % to 60 %		Approved
			25 KV		
Solderability (SMD)	15	J-STD-002	Condition B1	preconditions: Dry Bake 4 h ± 15 min @ 155 °C, Dip and Look Test (Leadless) Solder Angle:20-45° Solder temperature:245±5 °C Solder immersion time: 5+0/-0.5 s	Approved
	15		Condition D	preconditions: Dry Bake 4 h ± 15 min @ 155 °C, Resistance to Dissolution of Metallization Solder Angle:20-45° Solder temperature:260±5 °C Solder immersion time: 30+5/-0s	Approved
Electrical Characterization	30	User Spec.	measure electrical property@ 20 °C,150 °C, - 55 °C		Approved
Board Flex	30	AEC-Q200-005	bending 2 mm (Min), 60(+5) sec		Approved
Terminal Strength (SMD)	30	AEC-Q200-006	Push Off Force (N)		Approved
			17.7 N		
Low Temperature Storage Life	77	JESD22-A119	-55 °C, 1000 h		Approved